

ABSTRACT

There are provided a reflective mask blank, a reflective mask, a reflective mask manufacturing method, and a reflective mask correction technique capable of reducing time required for electron beam correction etching, even when a material used for a thin absorption film has a large extinction coefficient k to an EUV light. A reflective photomask blank (10) according to this embodiment has a substrate (1), a multi-layer reflective film (2), a capping layer (3), and a low reflective portion (5), in which the low reflective portion (5) is obtained by alternately depositing an absorption film (A) and an absorption film (B), the correction etching rate in the electron beam correction of the absorption film (A) is larger than the correction etching rate in the electron beam correction of the absorption film (B), and the absorption film (B) contains one or more elements selected from tin, indium, platinum, nickel, tellurium, silver, and cobalt.

FIG. 1